

Abstract

A method of using protective caps (160) applied to a first side of a wafer (150) in the production of microfabricated devices (152), such as micro-electro-mechanical systems (MEMS) devices. One cap (160) covers each microfabricated device or group respectively, such that a gap remains between adjacent protective caps. One or more etches are applied to the gaps between the caps to remove material and separate the wafer into separate units.